

Bipolar Transistors Silicon PNP Epitaxial Type

HN1A01FU

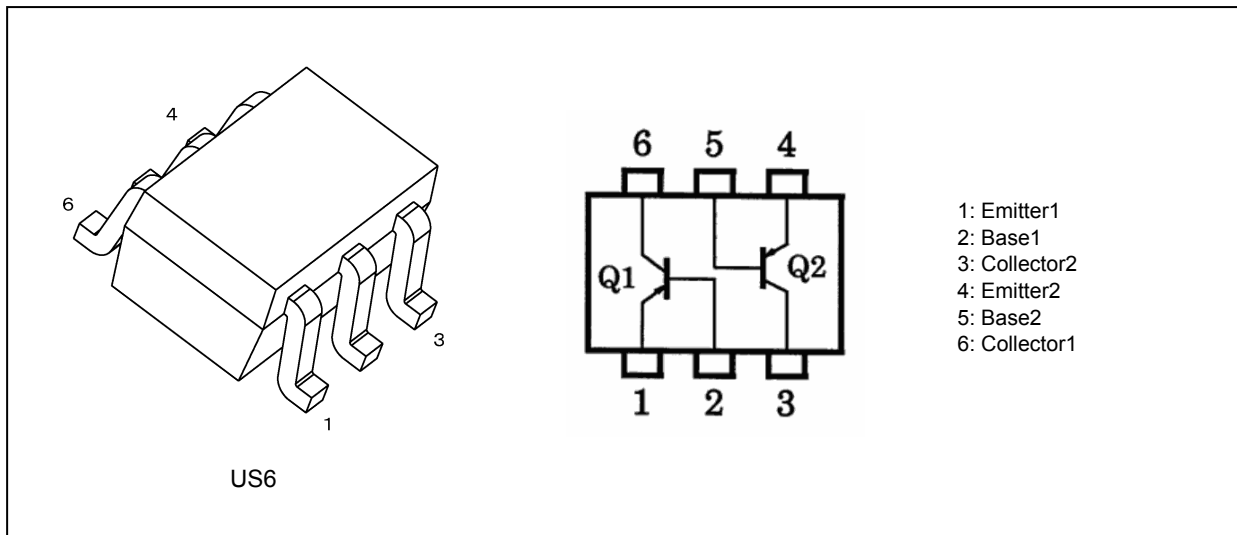
1. Applications

- Low-Frequency Amplifiers

2. Features

- (1) AEC-Q101 qualified (Please see the orderable part number list)
- (2) Small package (Dual type)
- (3) High voltage: $V_{CEO} = -50\text{ V}$
- (4) High collector current: $I_C = -150\text{ mA (max)}$
- (5) High h_{FE} : $h_{FE} = 120\text{ to }400$
- (6) Excellent h_{FE} linearity: $h_{FE}(I_C = -0.1\text{ mA})/h_{FE}(I_C = -2\text{ mA}) = 0.95\text{ (typ.)}$

3. Packaging and Internal Circuit



Start of commercial production

1991-01

4. Orderable part number

Orderable part number		AEC-Q101	Note
HN1A01FU-Y	HN1A01FU-Y,LF	—	General Use
	HN1A01FU-Y,LXGF	YES (Note 1)	Unintended Use (Note 1)
	HN1A01FU-Y,LXHF	YES	Automotive Use
HN1A01FU-GR	HN1A01FU-GR,LF	—	General Use
	HN1A01FU-GR,LXGF	YES (Note 1)	Unintended Use (Note 1)
	HN1A01FU-GR,LXHF	YES	Automotive Use

Note 1: For more information, please contact our sales or use the inquiry form on our website.

5. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25^\circ\text{C}$) (Q1, Q2 Common)

Characteristics		Symbol	Rating	Unit
Collector-base voltage		V_{CBO}	-50	V
Collector-emitter voltage		V_{CEO}	-50	V
Emitter-base voltage		V_{EBO}	-5	V
Collector current		I_C	-150	mA
Base current		I_B	-30	mA
Collector power dissipation (Note 4)		P_C	200	mW
Junction temperature	(Note 2)	T_j	150	$^\circ\text{C}$
	(Note 3)		125	
Storage temperature	(Note 2)	T_{stg}	-55 to 150	$^\circ\text{C}$
	(Note 3)		-55 to 125	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Note 2: For devices with the ordering part number ending in LF(T).

Note 3: For devices with the ordering part number ending in XGF(T, XHF(T).

Note 4: Device mounted on an FR4 board.(total rating)(25.4 mm × 25.4 mm × 1.6 mm, Cu pad: 0.32 mm² × 6)

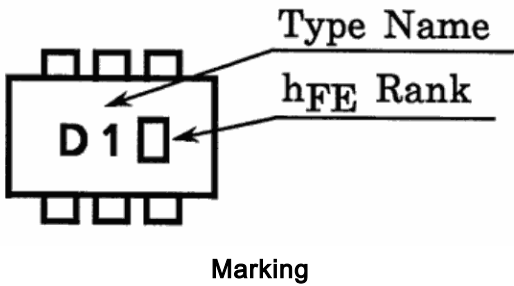
6. Electrical Characteristics (Unless otherwise specified, $T_a = 25^\circ\text{C}$) (Q1, Q2 Common)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Collector cut-off current	I_{CBO}		$V_{CB} = -50\text{ V}, I_E = 0\text{ mA}$	—	—	-0.1	μA
Emitter cut-off current	I_{EBO}		$V_{EB} = -5\text{ V}, I_C = 0\text{ mA}$	—	—	-0.1	
DC current gain	h_{FE}	(Note 5)	$V_{CE} = -6\text{ V}, I_C = -2\text{ mA}$	120	—	400	—
Collector-emitter saturation voltage	$V_{CE(sat)}$		$I_C = -100\text{ mA}, I_B = -10\text{ mA}$	—	-0.1	-0.3	V
Transition frequency	f_T		$V_{CE} = -10\text{ V}, I_C = -1\text{ mA}$	80	—	—	MHz
Collector output capacitance	C_{ob}		$V_{CB} = -10\text{ V}, I_E = 0\text{ mA}, f = 1\text{ MHz}$	—	4	7	pF

Note 5: h_{FE} classification Y (Y): 120 to 240, GR (G): 200 to 400

() marking symbol

7. Marking



8. Characteristics Curves (Note) (Q1, Q2 Common)

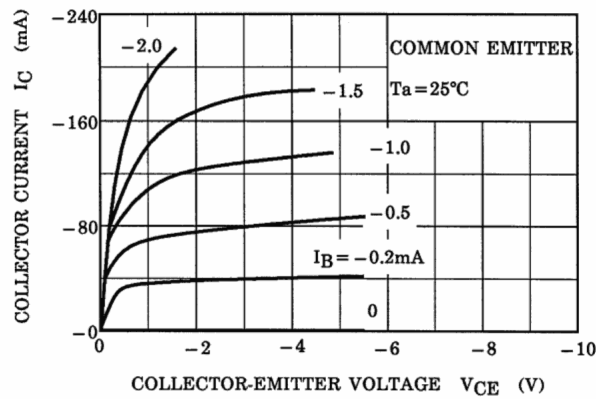


Fig. 8.1 IC - VCE

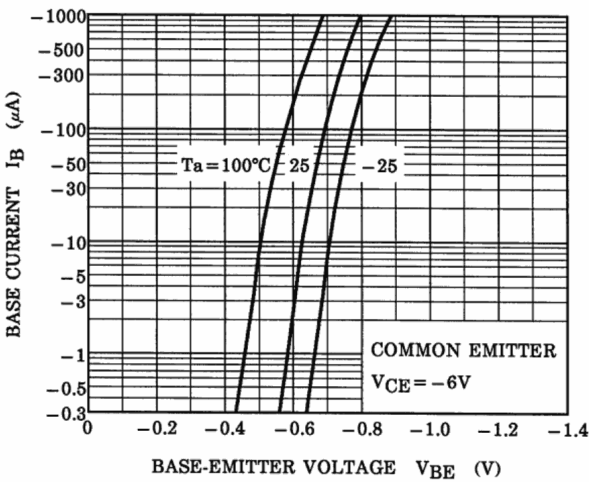


Fig. 8.2 IB - VBE

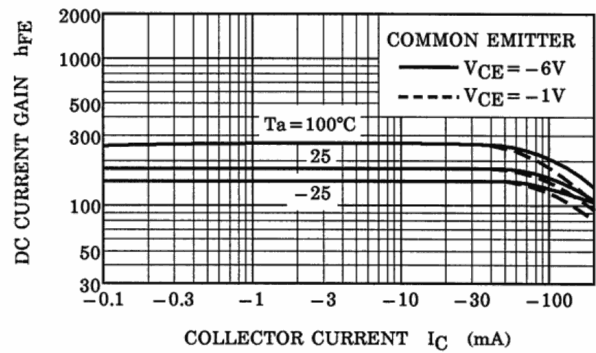


Fig. 8.3 hFE(ON) - IC

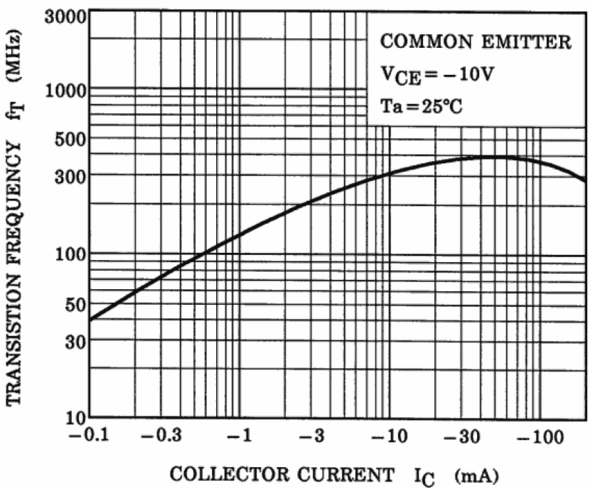


Fig. 8.4 fT - IC

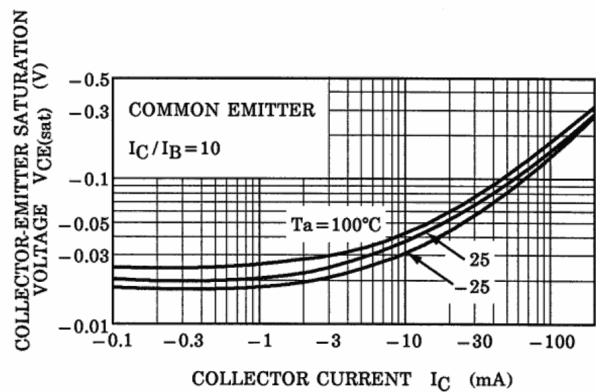


Fig. 8.5 VCE(sat) - IC

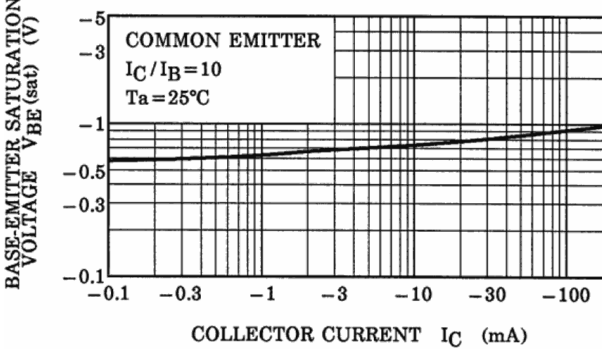


Fig. 8.6 VBE(sat) - IC

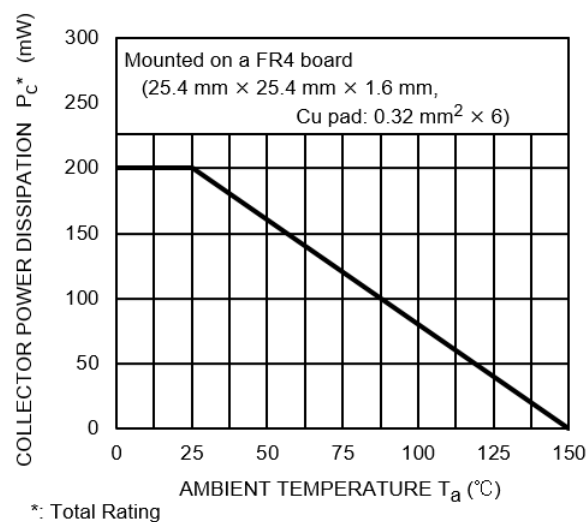
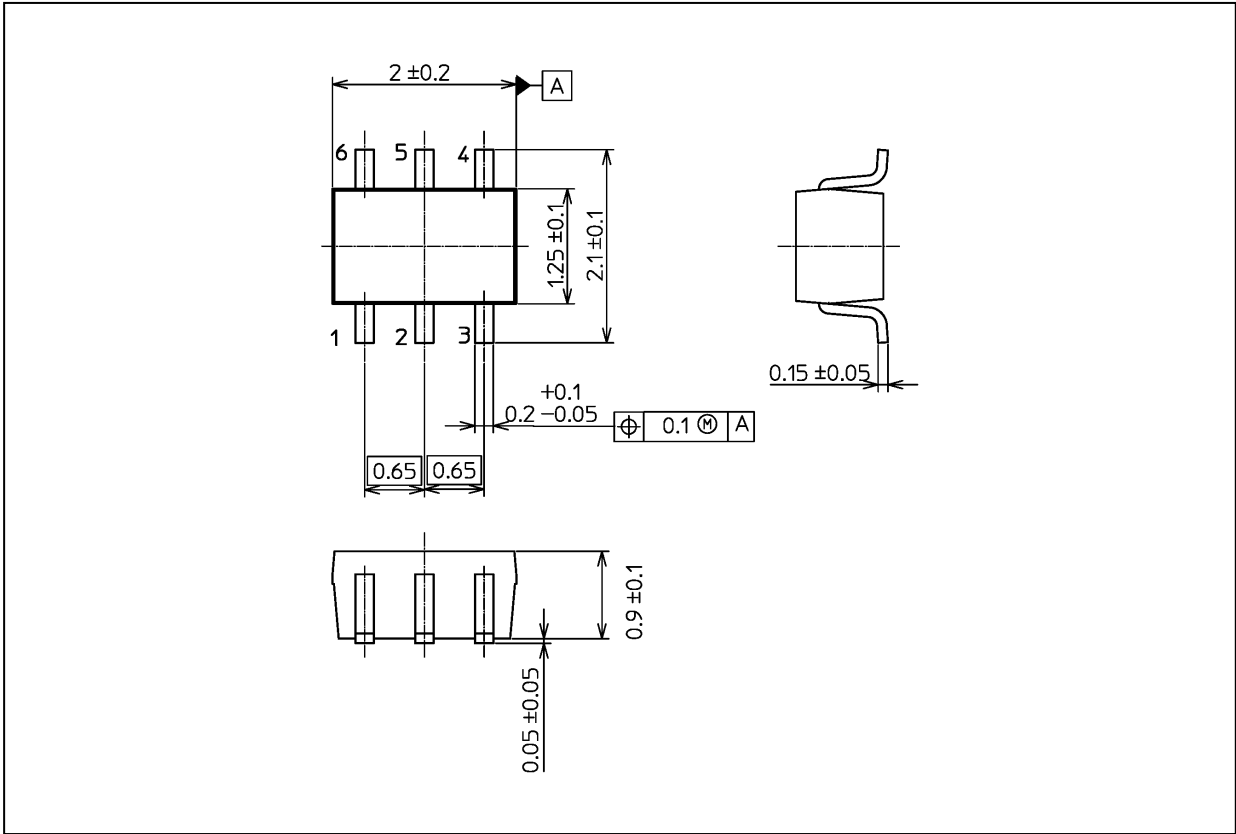


Fig. 8.7 $P_c - T_a$
Reference only with T_j of 150 °C.

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 6.8 mg (typ.)

Package Name(s)
Nickname: US6

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